

# MSKSEMI

SEMICONDUCTOR



ESD



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Product data sheet

[www.msksemi.com](http://www.msksemi.com)

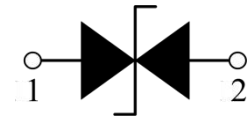
## Features

- ◆ 80 Watts peak pulse power ( $t_p = 8/20\mu s$ )
- ◆ Transient protection for high speed data lines to IEC 61000-4-2 (ESD)  $\pm 15kV$  (air),  $\pm 8kV$  (contact) IEC 61000-4-4 (EFT) 40A (5/50ns)
- ◆ Working voltages : 5V
- ◆ Protects One Power or I/O Port
- ◆ Low operating and clamping voltages
- ◆ Solid-state silicon avalanche technology

## Pin Description



## Schematic Diagram



DFN1006-2

## Applications

- ◆ Notebooks, Desktops, Servers and Video Graphics Cards
- ◆ USB Power & Data Line Protection
- ◆ Monitors and Flat Panel Displays
- ◆ I<sup>2</sup>C Bus Protection
- ◆ Portable Instrumentation
- ◆ Set Top Box

## Electrical Characteristics @ Ta=25°C unless otherwise

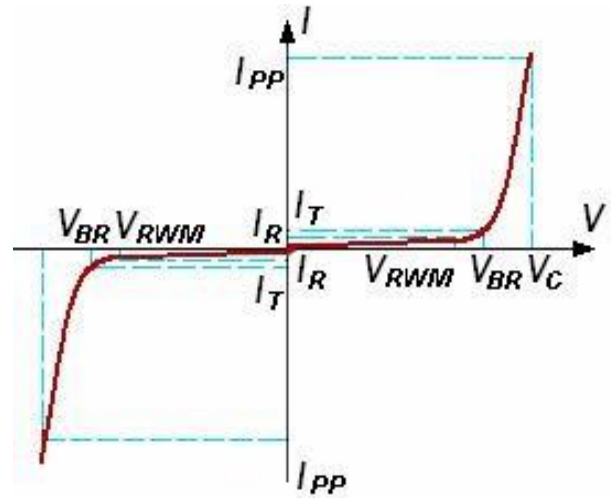
P/N	VRWM @IR		VBR@ImA	VC@1	VC@IPP		CJ
	V	$\mu A$	V	V	V	A	pF
		MAX	MIN	MAX	MAX		TYP
ESD5471X-MS	5	1	5.8	11.8	15	5	12

## Maximum Rating @ Ta=25°C unless otherwise specified

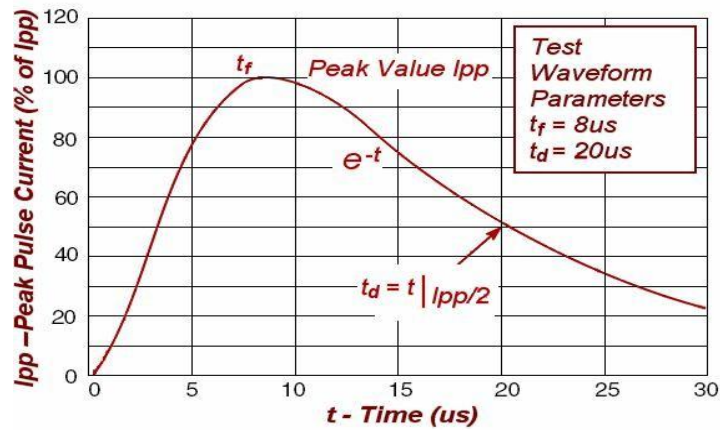
Symbol	Parameter	Ratings	Units
P <sub>PK</sub>	Peak Pulse Power ( $t_p = 8/20\mu s$ )	80	Watts
T <sub>L</sub>	Lead Soldering Temperature	260(10sec.)	°C
T <sub>J</sub>	Operating Temperature	-55 to +125	°C
T <sub>STG</sub>	Storage Temperature	-55 to +150	°C

**Electrical Parameter**

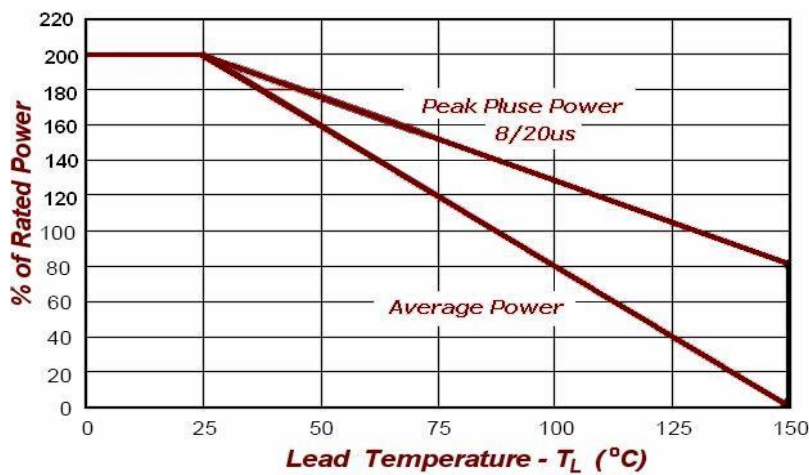
Symbol	Parameter
$I_{PP}$	Maximum Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$
$V_{RWM}$	Working Peak Reverse Voltage
$I_R$	Maximum Reverse Leakage Current @ $V_{RWM}$
$I_T$	Test Current
$V_{BR}$	Breakdown Voltage @ $I_T$



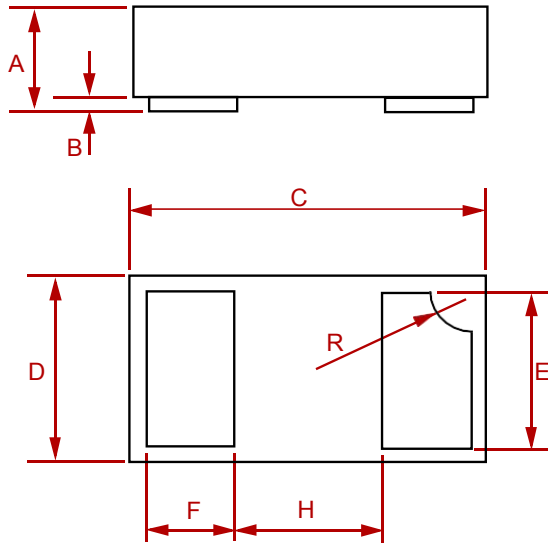
**FIG1: Pulse Waveform**



**FIG2: Power Derating**

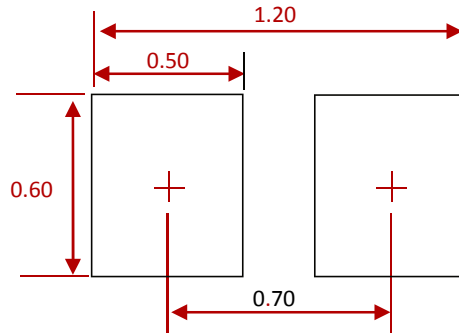


**PACKAGE MECHANICAL DATA**



Dim	Inches		Millimeters	
	MIN	MAX	MIN	MAX
A	0.0125	0.02	0.32	0.52
B	0.000	0.002	0.00	0.05
C	0.037	0.043	0.95	1.080
D	0.022	0.027	0.55	0.680
E	0.016	0.024	0.40	0.60
F	0.008	0.012	0.20	0.30
H	0.015Typ.		0.40Typ.	
R	0.001	0.005	0.05	0.15

**Suggested Pad Layout**



**NOTES:**

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

**REEL SPECIFICATION**

P/N	PKG	QTY
ESD5471X-MS	DFN1006-2	10000

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